



MMC560x-B Prototyping Board

MMC560x-B

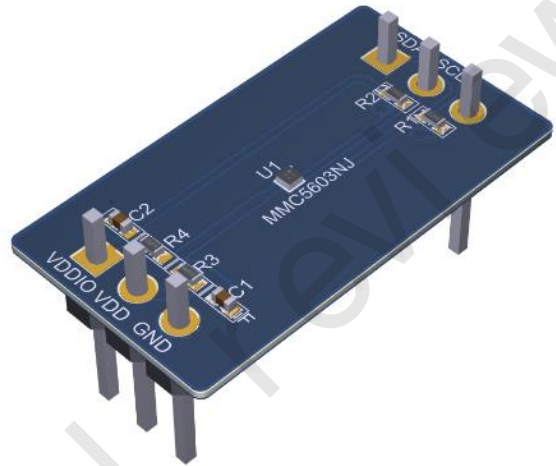
GENERAL DESCRIPTION

The MMC560x-B provides a convenient and easy way to evaluate and prototype with MMC560x the three axes magnetic sensor. The magnetic sensor and passive components needed for operations are SMT mounted on the board. Communication, power and ground pins of the MMC560x SMT device are brought out to standard 0.10 inch on center connections on the sides of the prototyping board. Wires can either be soldered directly to the prototyping board or DIP pins can be used with widely available breadboard kits.

For complete performance specifications of MMC560x refer to MMC560x datasheet.

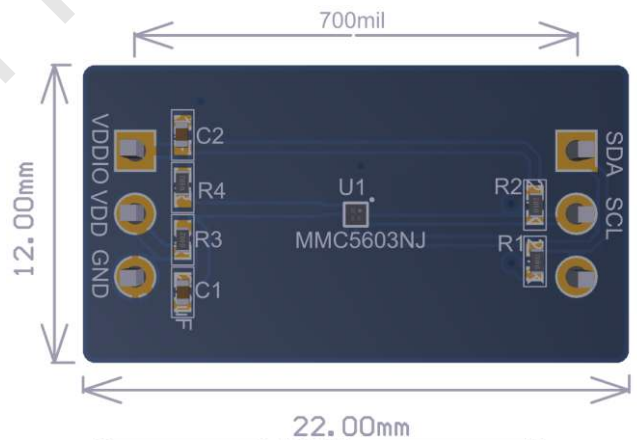
PIN DESCRIPTION

Pin	Name	Description
P1-1	VDDIO	I2C Supply Voltage
P1-2	VDD3V	Power
P1-3	GND	Ground
P2-1	SDA	I2C SDA
P2-2	SCL	I2C SCL
P2-3	NC	NOT CONNECTED



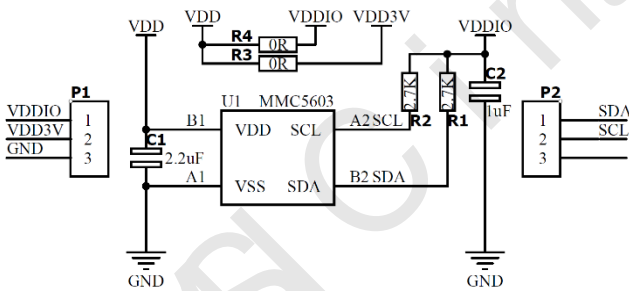
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PCB OUTLINE AND CONNECTION DIMENSIONS



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SCHEMATIC OF THE MMC560x-B



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